SLOVENSKI STANDARD
oSIST prEN IEC 61760-1:2025

01-september-2025

Tehnologija površinske montaže - 1. del: Standardna metoda za specifikacijo komponent za površinsko montažo (SMDs)

Surface mounting technology - Part 1: Standard method for the specification of surface mounting components (SMDs).

Technique du montage en surface - Partie 1: Méthode normalisée pour la spécification des composants pour montage en surface (CMS)

Ta slovenski standard je istoveten z: **prEN IEC 61760-1:2025**

ICS:

31.190	Sestavljeni elektronski elementi	Electronic component assemblies

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COMMITTEE DRAFT FOR VOTE (CDV)

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IEC TC 91 : ELECTRONICS ASSEMBLY TECHNOLOGY	
SECRETARIAT: Japan	SECRETARY: Mr Osamu IKEDA
OF INTEREST TO THE FOLLOWING COMMITTEES: TC 40,TC 47,TC 86	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:	
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TITLE:

Surface mounting technology - Part 1: Standard method for the specification of surface mounting components (SMDs).

PROPOSED STABILITY DATE: 2030

NOTE FROM TC/SC OFFICERS:

Link to Committee Draft for Vote (CDV) online document:

https://osd.iec.ch/#/editor/archive/1cd27be7-cf53-3e7d-e063-2b13000a52eb/en/CCDV/1

How to access

This link leads you to the Online Standards Development (OSD) platform for National Mirror Committee's (NMC) comments. The project draft may be found further down this document.

Resource materials

We recommend NCs to review the available materials to better understand the member commenting on the OSD platform. This includes the:

- OSD NC roles overview: here
- How to add and submit comments to the IEC: here

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